

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

ltc1174hvcn8-3.3#pbf

(Engineering Calculation)

PDIP

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**TOTAL MASS (g) : 0.50168**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.004216	1000000	8403.7578125		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.149760	975000	298516.78125		
		Iron (Fe)	7439-89-6	0.003686	24000	7347.30810547		
		Phosphorus (P)	7723-14-0	0.000046	300	91.6918563843		
		Zinc (Zn)	7440-66-6	0.000108	700	215.276535034		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.153600</b>	<b>1000000</b>	<b>306171.09375</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.012410	1000000	24737.4472656		
		<b>External Plating Total:</b>				<b>0.012410</b>	<b>1000000</b>	<b>24737.4472656</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.001228	1000000	2447.77392578		
<b>Internal Plating Total:</b>				<b>0.001228</b>	<b>1000000</b>	<b>2447.77392578</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001155	750000	2302.26293945		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000385	250000	767.420959473		
<b>Die Attach Total:</b>				<b>0.001540</b>	<b>1000000</b>	<b>3069.68383789</b>		
Encapsulation	FILLED EPOXY RESIN	Resin (EP)		0.078816	240000	157104.03125		
		Bromine (Br)	40039-93-8	0.003284	10000	6546.00146484		
		Silica (SiO2)	60676-86-0	0.236448	720000	471312.09375		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.009852	30000	19638.0039062		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000000	0	0		
		<b>Encapsulation Total:</b>				<b>0.328400</b>	<b>1000000</b>	<b>654600.0625</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000286	1000000	570.08416748		
					<b>TOTAL MASS (g) :</b>	<b>0.50168</b>		